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2/165, B81B 7/00(74) Agent: **SILVERBROOK, KIA**; Silverbrook Research Pty
Ltd, 393 Darling Street, Balmain, New South Wales 2041
(AU).

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BROOK RESEARCH PTY LTD** [AU/AU]; 393 Darling
Street, Balmain, New South Wales 2041 (AU).

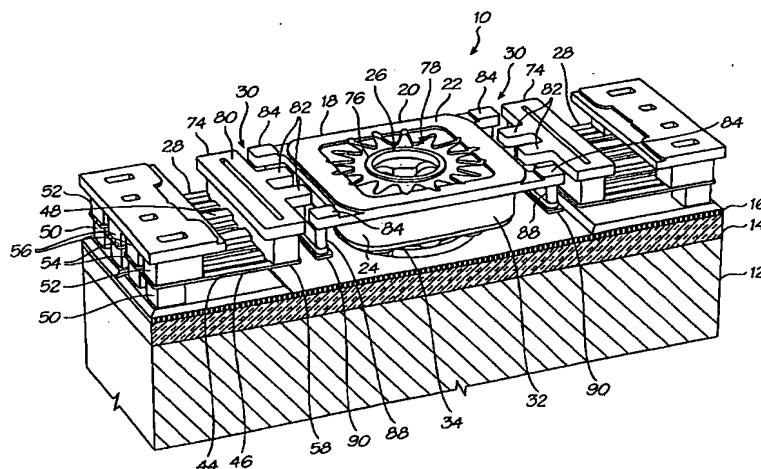
(72) Inventor; and

(75) Inventor/Applicant (for US only): **SILVERBROOK,
KIA** [AU/AU]; Silverbrook Research Pty Ltd, 393 Darling
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(54) Title: SYMMETRICALLY ACTUATED INK EJECTION COMPONENTS FOR AN INK JET PRINthead CHIP

(57) **Abstract:** A printhead chip for an ink jet printhead that includes a plurality of nozzle arrangements on a silicon wafer substrate (12). Each nozzle arrangement (10) has an active and static ink ejection structures positioned on the substrate. The active ink ejection structure (20) has a roof (22) with an ink ejection port (26) defined in the roof. The active ink ejection structure (20) and the static ink ejection structure (34) together define a nozzle chamber (42) in fluid communication with an ink supply. At least two thermal bend actuators (28) are operatively arranged with respect to the active ink ejection structure to displace the active ink ejection structure with respect to the static ink ejection structure towards and away from the substrate to reduce and increase a volume of the nozzle chamber to eject an ink drop from the nozzle chamber. The actuators (28) are configured and connected to the active ink ejection structure to impart substantially rectilinear movement to the active ink ejection structure.